



BR3 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 19.10%	Copper (Cu)	7440-50-8	455.82	99.98	190,885.64
	Phosphorus (P)	7723-14-0	0.005	0.0010	1.9
	Arsenic (As)	7440-38-2	0.005	0.0010	1.9
	Tin (Sn)	7440-31-5	0.005	0.0010	1.9
	Oxygen (O)	7782-44-7	0.002	0.0005	1.0
	Sulfur (S)	7704-34-9	0.055	0.0120	22.9
	Iron (Fe)	7439-89-6	0.003	0.0007	1.3
	Nickel (Ni)	7440-02-0	0.001	0.0003	0.6
	Bismuth (Bi)	7440-69-9	0.009	0.0020	3.8
	Antimony (Sb)	1309-64-4	0.009	0.0020	3.8
	Lead (Pb)	7439-92-1	0.002	0.0005	1.0
	Zinc (Zn)	7440-66-6	0.001	0.0003	0.6
	Total			455.92	
Solder Wafer 0.33%	Lead (Pb)	7439-92-1	7.40	92.50	3,098.9
	Tin (Sn)	7440-31-5	0.40	5.00	167.5
	Silver (Ag)	7440-22-4	0.20	2.50	83.8
Total			8.00		
Chip 0.33%	Silicon (Si)	7440-21-3	8.00	100.00	3,350.2
	Total			8.00	
Case 28.37%	Epoxy	25928-94-3	677.40	100.00	283,677.6
	Total			677.40	
Potting 51.64%	Epoxy	25928-94-3	1,233.06	100.00	516,373.7
	Total			1,233.06	
Plating 0.23%	Tin (Sn)	7440-31-5	5.55	100.00	2,322.1
	Total			5.55	
Total mass (mg)			2387.92		